



## Chip Inductors for RF Applications (Wire wound-open)

FASTRON wire wound chip inductors are designed particularly for RF applications that require optimal Q on high frequency circuits. Its gold flash pad metallization provides better solderability for a higher yield in your production. In addition, their encapsulation not only protects the winding but also allows surface mount assembly. It comes in compact sizes (from 0402 to 1812) available in reel packing. Inductance values between those listed in this catalog are mostly available on request. Ferrite core versions are also available for selected case sizes for applications which require higher inductances in a smaller case size.

- Applications**
- Used in LC resonant circuits such as oscillator and signal generators, impedance matching, RF filters etc.
  - Mobile Telecommunication: GSM, CDMA, TCDMA, cordless phones, 2 way radio
  - Automotive Subsystems: TPMS, Keyless Entry, Anti-Theft, GPS
  - Wireless Communication: W-LAN, WIFI, WIMAX, RFID, Bluetooth
  - Non-magnetic versions for medical imaging applications: ASM series

### Technical Data

|   |   |
|---|---|
| L – Value (rated inductance)                | ≥ 1 MHz measured with HP 4286A RF LCR meter at frequency $f_L$<br>< 1 MHz measured with Bode 100 Vector Network Analyzer at frequency $f_L$   |
| Q – Factor (min)                            | ≥ 1 MHz measured with HP 4287A RF LCR meter at frequency $f_Q$<br>< 1 MHz measured with Bode 100 Vector Network Analyzer at frequency $f_Q$   |
| SRF (min)                                   | Measured with HP 8753ES Network Analyzer  |
| DCR (max)                                   | Measured at 25°C  |
| Operating Temperature                       | For ceramic core from -40°C to +150°C (Including component self-heating)<br>For ferrite core from -40°C to +85°C  |
| Surface Finishing                           | Epoxy molded flat top for perfect pick and place assembly   |
| Pad Metallization                           | Gold flash as top layer   |
| Wire Termination                            | Spot welding  |
| Recommended soldering method                | Reflow  |
| Moisture Sensitivity Levels (MSL)           | MSL Level 1, indicating unlimited floor life at ≤ 30°C / 85% relative humidity  |
| Solderability                               | Using lead free solder (Sn 99.9) at 260°C ± 5°C for 5 ± 0.5 seconds, min 90% solder coverage of metallization<br>Standard: IEC 68-2-20 (Ta)   |
| Resistance to Soldering Heat                | Resistant to 260°C ± 5°C for 10 ± 1 seconds<br>Standard: IEC 68-2-20 (Tb)   |
| Resistance to Solvent                       | Resistant to Isopropyl alcohol for 5 ± 0.5 minutes at 23°C ± 5°C<br>Standard: IEC 68-2-45   |
| Climatic Test                               | Defined by the following standards<br>IEC 68-2-1 for Cold test: -55°C for 96 hours<br>IEC 68-2-2 for Dry heat test: +85°C for ferrite core and 125°C for ceramic core for 96 hours<br>IEC 60068-2-78 for Humidity test: 40°C at RH 95% for 4 days |
| Thermal Shock Test                          | Temperature cycle (ceramic) : -40°C to +125°C to -40°C<br>Temperature cycle (ferrite) : -40°C to +85°C to -40°C<br>Max/Min temperature duration: 15 minutes<br>Temperature transition duration: 5 minutes<br>Cycles: 25<br>Standard: MIL-STD-202G |
| Adhesion of Soldered Component (Shear Test) | Components withstand a pushing force of 10N for 10 ± 1 seconds<br>Standard: IEC 60068-2-21, method Ue3  |
| Mechanical Shock                            | Mil-Std 202 Method 213, Condition C<br>3 axis, 6 times, total 18 shocks<br>100 G, 6 ms, half-sine   |
| Vibration                                   | Mil-Std 202 Method 204<br>20 mins at 5G<br>10 Hz to 2000 Hz<br>12 cycles each of 3 orientations   |

**Ordering Code** Example: 0402AS-1N0X-YY ➔ **0402AS-1N0K-01**

**0402**    **AS**    -    **1N0**    **X**    -    **YY**  
(Case Size) (Core Type)    (Inductance Value) (Tolerance)    (Packing Code)

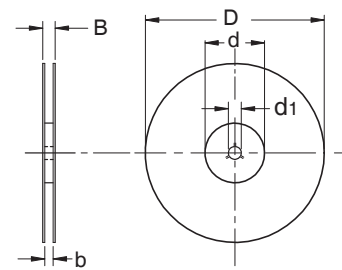
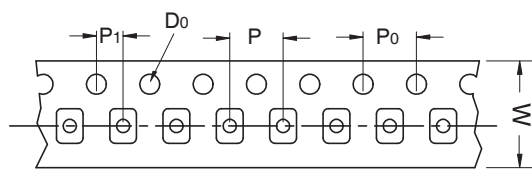
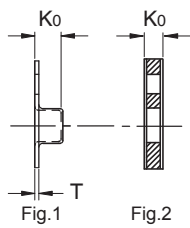
- Case Sizes    - 0402, 0603, 0805, 1008, 1206, 1210, 1812
- Core Type    - AS, AQ, ASM (Ceramic), F (Ferrite), AF (Ceramic & Ferrite)
- Tolerances    - F (1%), G (2%), A (3%), J (5%), K (10%), M (20%)
- Packing Code - 01, 04, 08 (Taped / Reel)

Technical Data



### Chip Inductors for RF Applications (Wire wound-open)

Packing Specification



drawing only schematic, see table

| Type | Packing Code | D   | D0   | d   | d1 | B    | b    | W  | P | P0 | P1 | K0   | T    | Fig |
|------|--------------|-----|------|-----|----|------|------|----|---|----|----|------|------|-----|
| 0402 | 01,08        | 180 | 1.55 | 60  | 13 | 12.7 | 8.4  | 8  | 2 | 4  | 2  | 0.6  | -    | 2   |
| 0603 | 01,08        | 180 | 1.55 | 60  | 13 | 12.7 | 8.4  | 8  | 4 | 4  | 2  | 1.0  | 0.25 | 1   |
| 0603 | 04           | 330 | 1.55 | 100 | 13 | 14.4 | 8.4  | 8  | 4 | 4  | 2  | 1.0  | 0.25 | 1   |
| 0805 | 01           | 180 | 1.55 | 60  | 13 | 12.7 | 8.4  | 8  | 4 | 4  | 2  | 1.63 | 0.25 | 1   |
| 0805 | 04           | 330 | 1.55 | 100 | 13 | 14.4 | 8.4  | 8  | 4 | 4  | 2  | 1.63 | 0.25 | 1   |
| 1008 | 01           | 180 | 1.50 | 60  | 13 | 12.7 | 8.4  | 8  | 4 | 4  | 2  | 2.23 | 0.3  | 1   |
| 1008 | 04           | 330 | 1.55 | 100 | 13 | 14.4 | 8.4  | 8  | 4 | 4  | 2  | 1.63 | 0.25 | 1   |
| 1206 | 01           | 180 | 1.50 | 60  | 13 | 18.4 | 13.7 | 12 | 4 | 4  | 2  | 1.8  | 0.3  | 1   |
| 1206 | 04           | 330 | 1.50 | 100 | 13 | 18.4 | 12.4 | 12 | 4 | 4  | 2  | 1.8  | 0.3  | 1   |
| 1210 | 01           | 180 | 1.55 | 60  | 13 | 18.4 | 13.7 | 12 | 8 | 4  | 2  | 2.55 | 0.3  | 1   |
| 1210 | 04           | 330 | 1.55 | 100 | 13 | 18.4 | 12.4 | 12 | 8 | 4  | 2  | 2.55 | 0.3  | 1   |
| 1812 | 01           | 180 | 1.50 | 60  | 13 | 18.4 | 13.7 | 12 | 8 | 4  | 2  | 3.70 | 0.35 | 1   |
| 1812 | 04           | 330 | 1.50 | 100 | 13 | 18.4 | 12.4 | 12 | 8 | 4  | 2  | 3.70 | 0.35 | 1   |

Packing Specification